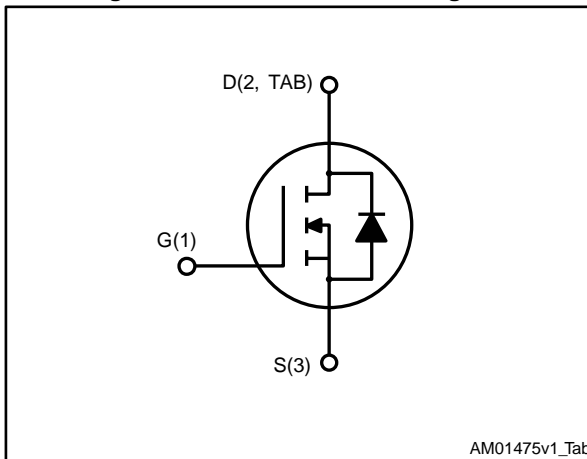


N-channel 60 V, 32 mΩ typ., 24 A STripFET™ II Power MOSFET in a DPAK package

Datasheet - production data



Figure 1: Internal schematic diagram



Features

Order code	V _{DS}	R _{DS(on)} max.	I _D	P _{TOT}
STD19NF06L	60 V	40 mΩ	24 A	60 W

- Exceptional dv/dt capability
- 100% avalanche tested
- Low gate charge

Applications

- Switching applications

Description

This Power MOSFET is the latest development of STMicroelectronics relative to the unique “Single Feature Size™” strip-based process. The resulting transistor shows a very high packing density for low on-resistance, rugged avalanche characteristics and less critical alignment steps by achieving a remarkable manufacturing reproducibility.

Table 1: Device summary

Order code	Marking	Package	Packing
STD19NF06L	19NF06L	DPAK	Tape and Reel

Contents

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- 3 Test circuits 8**
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1 Electrical ratings

Table 2: Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{DS}	Drain-source voltage	60	V
V_{GS}	Gate-source voltage	± 18	V
I_D	Drain current (continuous) at $T_{case} = 25\text{ }^\circ\text{C}$	24	A
	Drain current (continuous) at $T_{case} = 100\text{ }^\circ\text{C}$	17	
$I_{DM}^{(1)}$	Drain current (pulsed)	96	A
P_{TOT}	Total dissipation at $T_{case} = 25\text{ }^\circ\text{C}$	60	W
$dv/dt^{(2)}$	Peak diode recovery voltage slope	10	V/ns
$E_{AS}^{(3)}$	Single pulse avalanche energy	225	mJ
T_{stg}	Storage temperature range	-55 to 175	$^\circ\text{C}$
T_j	Operating junction temperature range		

Notes:

- (1) Pulse width is limited by safe operating area.
 (2) $I_{SD} \leq 24\text{ A}$, $di/dt \leq 300\text{ A/ns}$, $V_{DD} = 80\% V_{(BR)DSS}$
 (3) Starting $T_j = 25\text{ }^\circ\text{C}$, $I_D = 14\text{ A}$, $V_{DD} = 60\text{ V}$.

Table 3: Thermal data

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case	2.5	$^\circ\text{C/W}$
$R_{thj-pcb}^{(1)}$	Thermal resistance junction-pcb	350	

Notes:

- (1) When mounted on a 1-inch² FR-4, 2 Oz copper board.

2 Electrical characteristics

($T_{\text{case}} = 25\text{ °C}$ unless otherwise specified)

Table 4: Static

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(\text{BR})\text{DSS}}$	Drain-source breakdown voltage	$V_{\text{GS}} = 0\text{ V}$, $I_{\text{D}} = 250\text{ }\mu\text{A}$	60			V
I_{DSS}	Zero gate voltage drain current	$V_{\text{GS}} = 0\text{ V}$, $V_{\text{DS}} = 60\text{ V}$			1	μA
		$V_{\text{GS}} = 0\text{ V}$, $V_{\text{DS}} = 60\text{ V}$, $T_{\text{case}} = 125\text{ °C}$ ⁽¹⁾			10	
I_{GSS}	Gate-body leakage current	$V_{\text{DS}} = 0\text{ V}$, $V_{\text{GS}} = \pm 18\text{ V}$			± 100	nA
$V_{\text{GS(th)}}$	Gate threshold voltage	$V_{\text{DS}} = V_{\text{GS}}$, $I_{\text{D}} = 250\text{ }\mu\text{A}$	1		2.5	V
$R_{\text{DS(on)}}$	Static drain-source on-resistance	$V_{\text{GS}} = 10\text{ V}$, $I_{\text{D}} = 12\text{ A}$		32	40	m Ω
		$V_{\text{GS}} = 5\text{ V}$, $I_{\text{D}} = 12\text{ A}$			50	

Notes:

⁽¹⁾Defined by design, not subject to production test.

Table 5: Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{ISS}	Input capacitance	$V_{\text{DS}} = 25\text{ V}$, $f = 1\text{ MHz}$, $V_{\text{GS}} = 0\text{ V}$	-	660	-	μF
C_{OSS}	Output capacitance		-	170	-	
C_{RSS}	Reverse transfer capacitance		-	70	-	
Q_{g}	Total gate charge	$V_{\text{DD}} = 30\text{ V}$, $I_{\text{D}} = 20\text{ A}$, $V_{\text{GS}} = 5\text{ V}$ (see Figure 13: "Test circuit for gate charge behavior")	-	13	-	nC
Q_{gs}	Gate-source charge		-	3.5	-	
Q_{gd}	Gate-drain charge		-	8	-	

Table 6: Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{\text{d(on)}}$	Turn-on delay time	$V_{\text{DD}} = 30\text{ V}$, $I_{\text{D}} = 10\text{ A}$, $R_{\text{G}} = 4.7\text{ }\Omega$, $V_{\text{GS}} = 5\text{ V}$ (see Figure 12: "Test circuit for resistive load switching times" and Figure 17: "Switching time waveform")	-	11	-	ns
t_{r}	Rise time		-	50	-	
$t_{\text{d(off)}}$	Turn-off delay time		-	20	-	
t_{f}	Fall time		-	12	-	

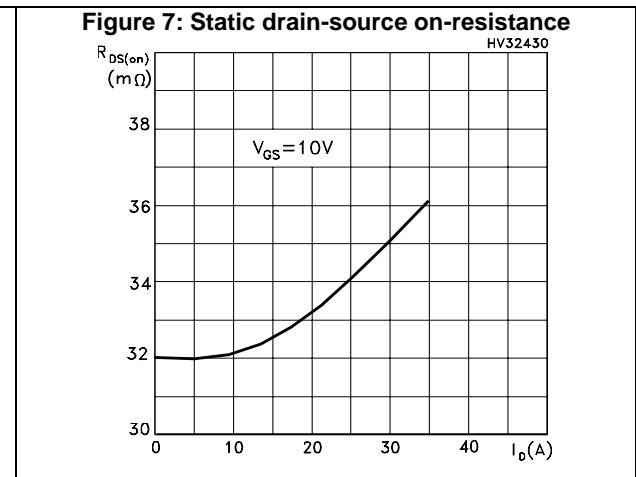
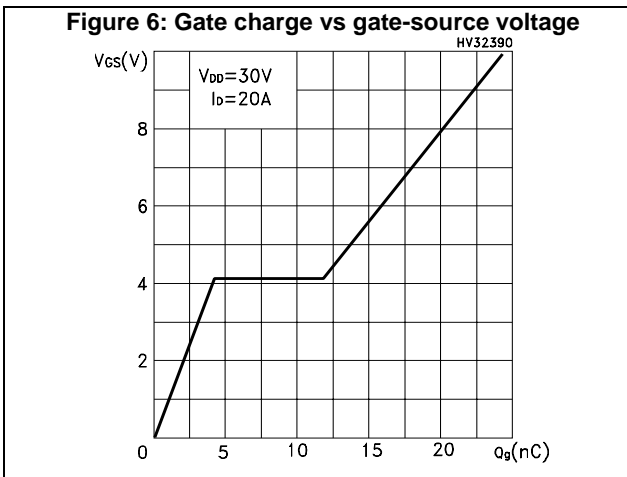
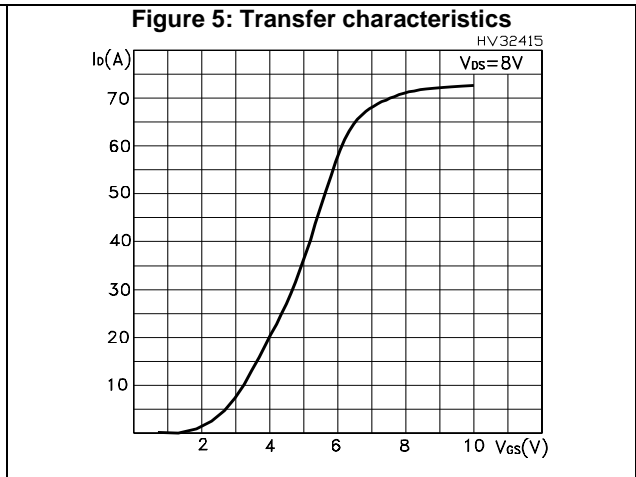
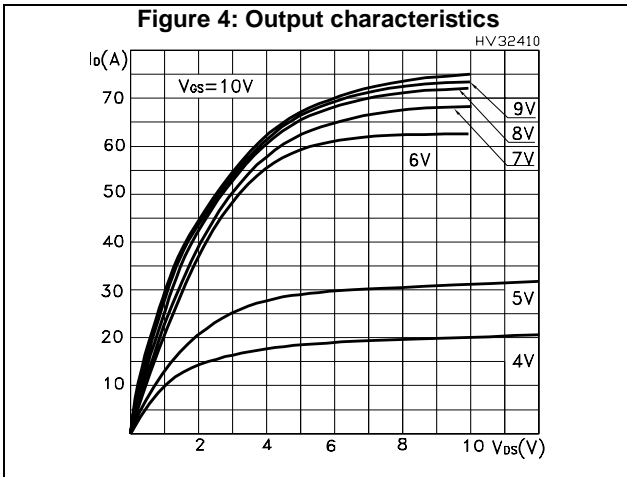
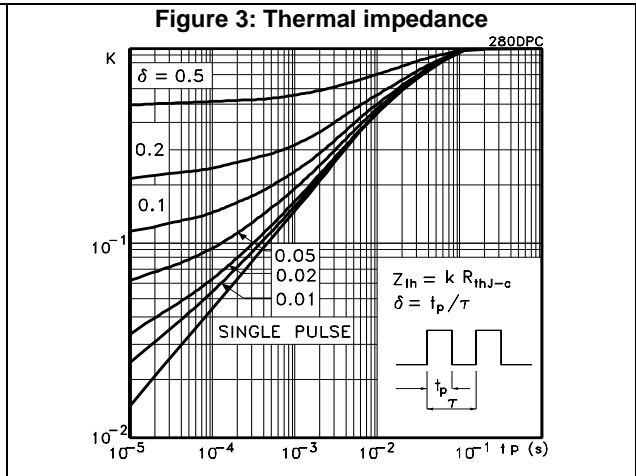
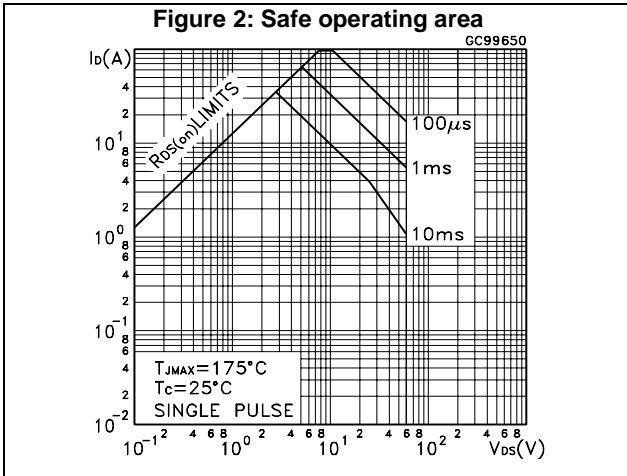
Table 7: Source-drain diode

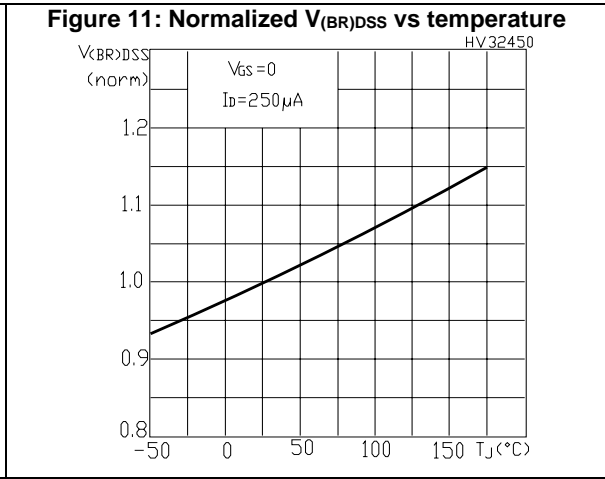
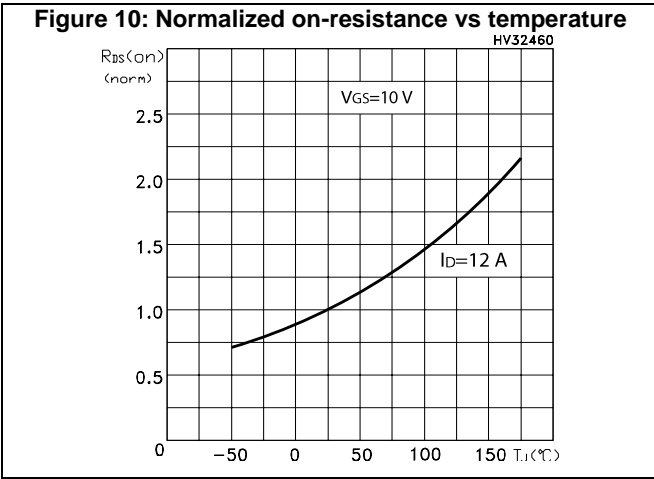
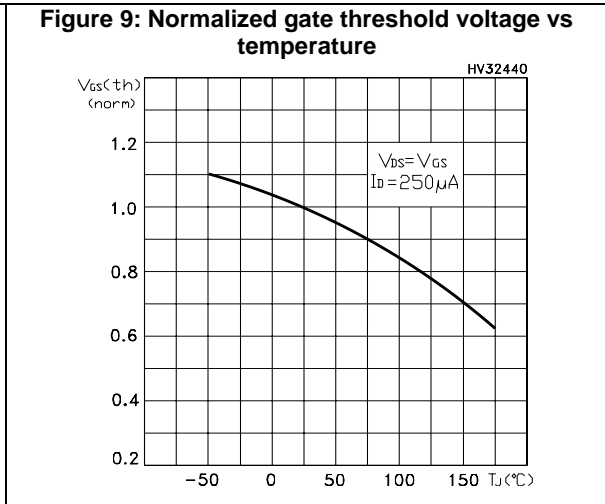
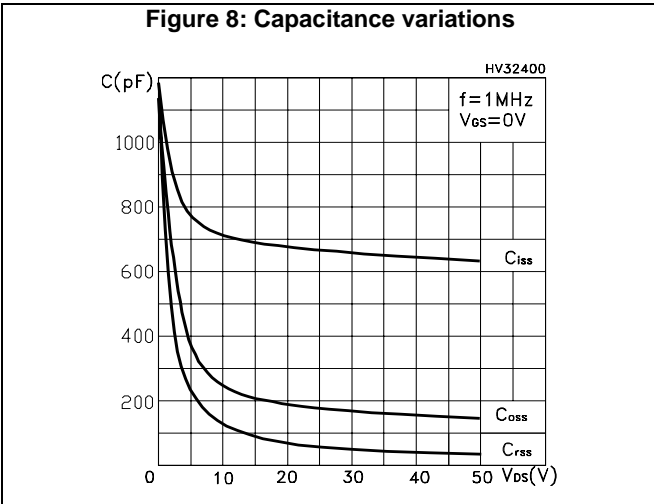
Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current		-		24	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		96	A
$V_{SD}^{(2)}$	Forward on voltage	$V_{GS} = 0\text{ V}$, $I_{SD} = 24\text{ A}$	-		1.5	V
t_{rr}	Reverse recovery time	$I_{SD} = 20\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$, $V_{DD} = 20\text{ V}$, $T_J = 150\text{ }^\circ\text{C}$ (see Figure 14: "Test circuit for inductive load switching and diode recovery times")	-	56		ns
Q_{rr}	Reverse recovery charge		-	108		nC
I_{RRM}	Reverse recovery current		-	4		A

Notes:

- (1) Pulse width is limited by safe operating area.
(2) Pulse test: pulse duration = 300 μs , duty cycle 1.5%.

2.1 Electrical characteristics (curves)





3 Test circuits

Figure 12: Test circuit for resistive load switching times



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Figure 13: Test circuit for gate charge behavior



AM01469v1

Figure 14: Test circuit for inductive load switching and diode recovery times



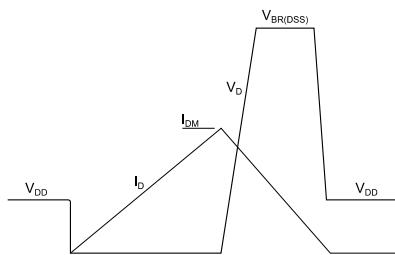
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Figure 15: Unclamped inductive load test circuit



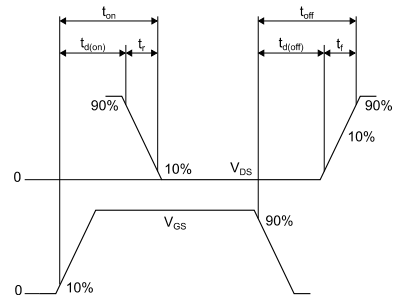
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Figure 16: Unclamped inductive waveform



AM01472v1

Figure 17: Switching time waveform



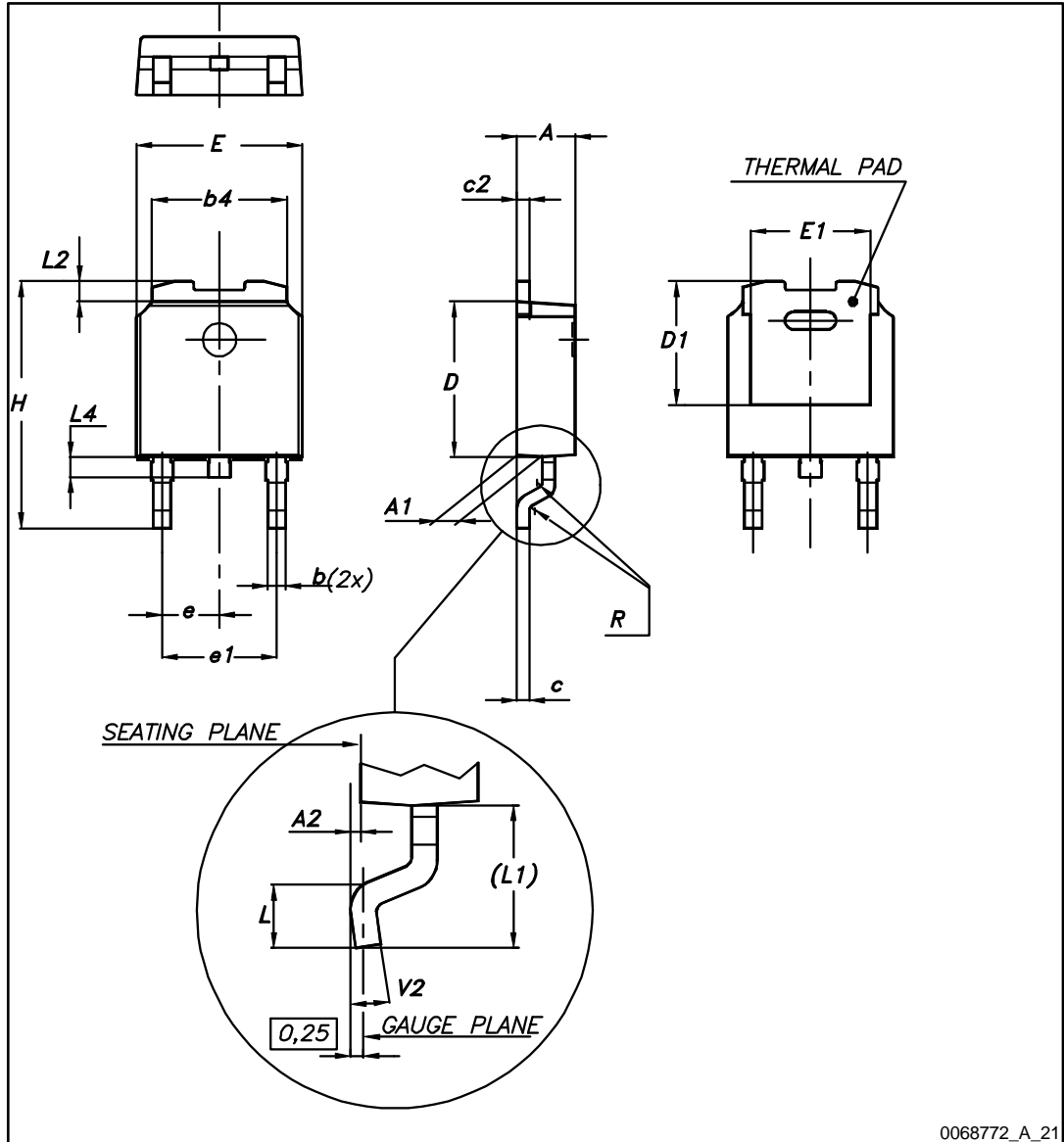
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4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

4.1 DPAK (TO-252) type A mechanical data

Figure 18: DPAK (TO-252) type A package outline



0068772_A_21

Table 8: DPAK (TO-252) type A mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	2.20		2.40
A1	0.90		1.10
A2	0.03		0.23
b	0.64		0.90
b4	5.20		5.40
c	0.45		0.60
c2	0.48		0.60
D	6.00		6.20
D1	4.95	5.10	5.25
E	6.40		6.60
E1	4.60	4.70	4.80
e	2.16	2.28	2.40
e1	4.40		4.60
H	9.35		10.10
L	1.00		1.50
(L1)	2.60	2.80	3.00
L2	0.65	0.80	0.95
L4	0.60		1.00
R		0.20	
V2	0°		8°

4.2 DPAK (TO-252) type C mechanical data

Figure 19: DPAK (TO-252) type C package outline

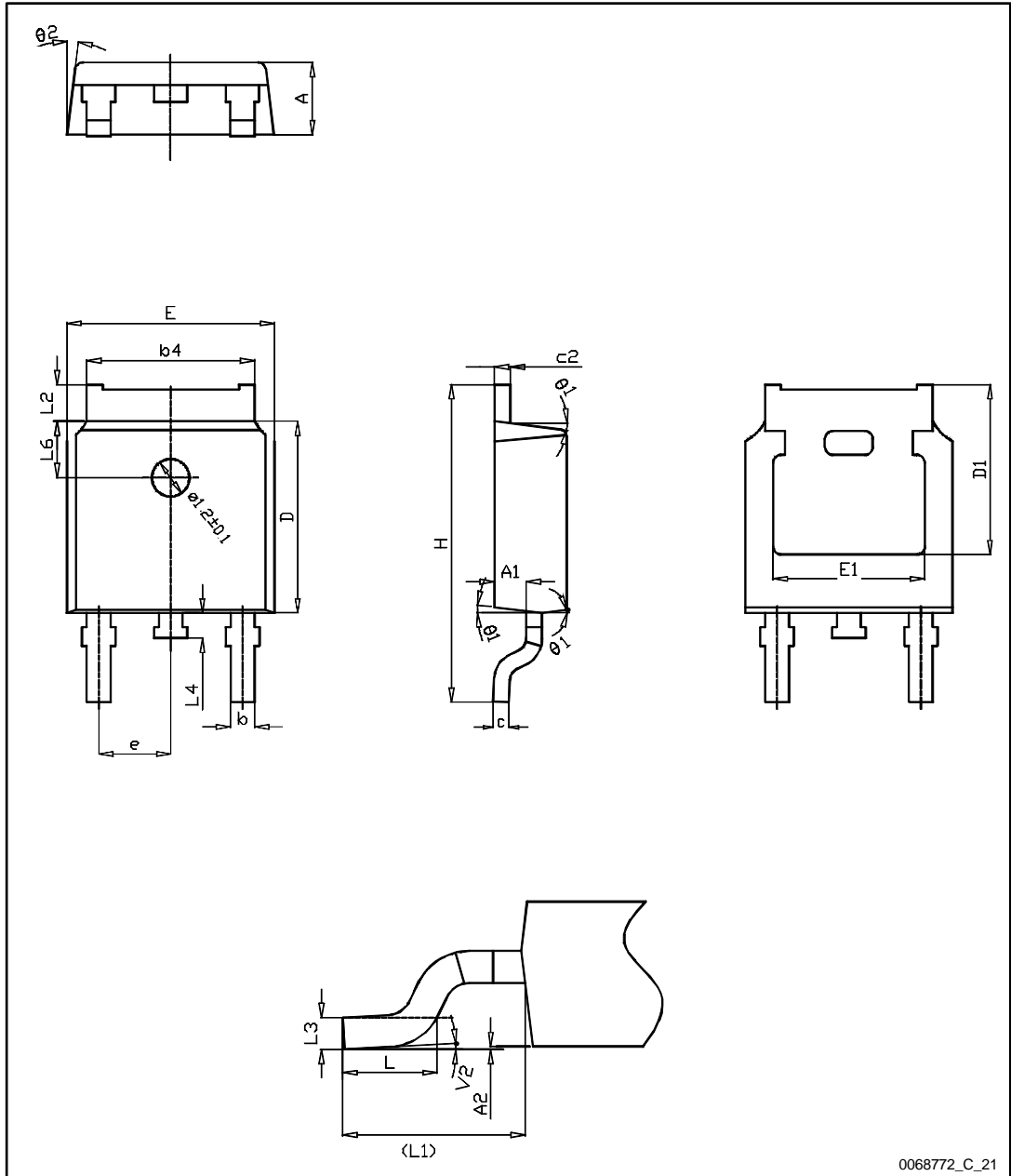
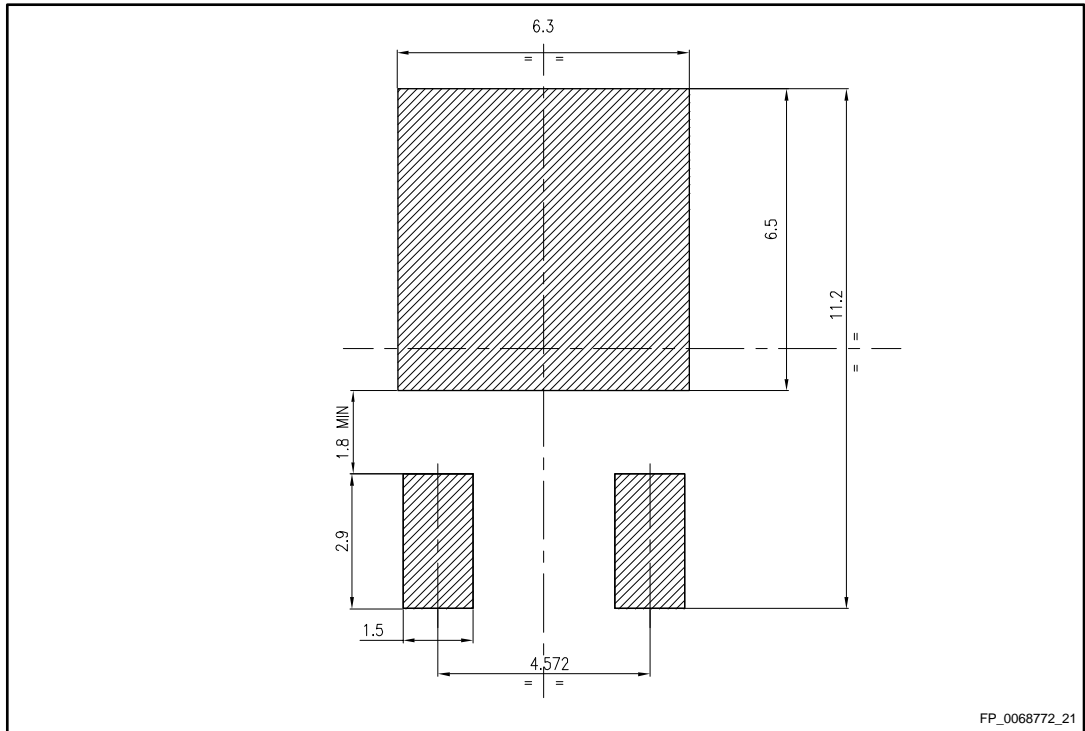


Table 9: DPAK (TO-252) type C mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	2.20	2.30	2.38
A1	0.90	1.01	1.10
A2	0.00		0.10
b	0.72		0.85
b4	5.13	5.33	5.46
c	0.47		0.60
c2	0.47		0.60
D	6.00	6.10	6.20
D1	5.25		
E	6.50	6.60	6.70
E1	4.70		
e	2.186	2.286	2.386
H	9.80	10.10	10.40
L	1.40	1.50	1.70
L1	2.90 REF		
L2	0.90		1.25
L3	0.51 BSC		
L4	0.60	0.80	1.00
L6	1.80 BSC		
θ1	5°	7°	9°
θ2	5°	7°	9°
V2	0°		8°

Figure 20: DPAK (TO-252) recommended footprint (dimensions are in mm)



4.3 DPAK (TO-252) packing information

Figure 21: DPAK (TO-252) tape outline

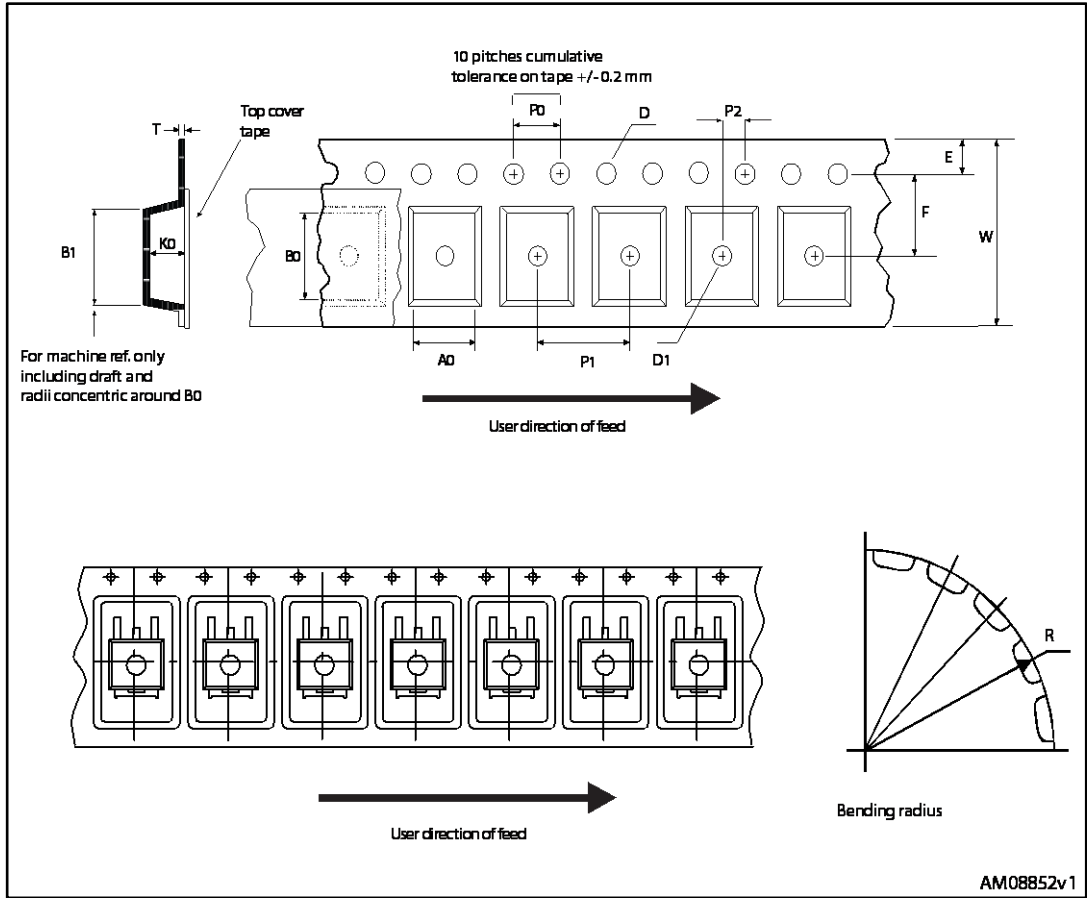


Figure 22: DPAK (TO-252) reel outline

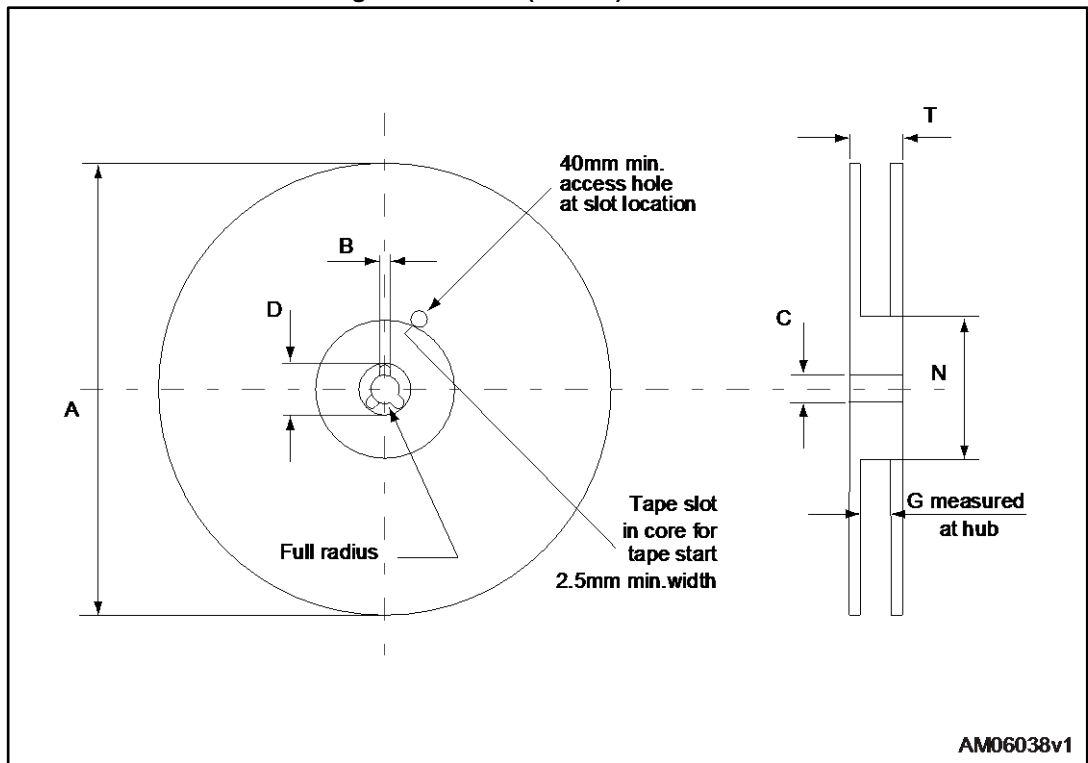


Table 10: DPAK (TO-252) tape and reel mechanical data

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	6.8	7	A		330
B0	10.4	10.6	B	1.5	
B1		12.1	C	12.8	13.2
D	1.5	1.6	D	20.2	
D1	1.5		G	16.4	18.4
E	1.65	1.85	N	50	
F	7.4	7.6	T		22.4
K0	2.55	2.75			
P0	3.9	4.1	Base qty.		2500
P1	7.9	8.1	Bulk qty.		2500
P2	1.9	2.1			
R	40				
T	0.25	0.35			
W	15.7	16.3			

5 Revision history

Table 11: Document revision history

Date	Revision	Changes
03-Nov-2016	1	First release.

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